

# Final Product/Process Change Notification Document #:FPCN22922X

Issue Date:22 May 2020

Title of Change:	Base and Submodule S	Base and Submodule Substrate Change and Max Height Change for SB3229/SB3230/SB3231.		
Proposed First Ship date:	29 Aug 2020 or earlier if approved by customer			
Contact Information:	Contact your local ON Semiconductor Sales Office or <a href="mailto:Jimmy.Zhang@onsemi.com">Jimmy.Zhang@onsemi.com</a>			
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timing	Contact your local ON Semiconductor Sales Office or <a href="PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.  Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local ON	Contact your local ON Semiconductor Sales Office or <u>Tara.McDonald@onsemi.com</u>		
Type of Notification:	days prior to implemer ON Semiconductor will	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>		
Marking of Parts/ Traceability of Change:		Base substrate will change from white to a yellow/brown color. Affected products will be identified by workorder number.		
Change Category:	Assembly Change	Assembly Change		
Change Sub-Category(s):	Material Change, Data	Material Change, Datasheet/Product Doc change		
Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		

### **Description and Purpose:**

ON Semiconductor Burlington, Canada

ON Semiconductor wishes to announce the following changes:

	Before Change Description	After Change Description
Base and submodule substrate	96% AI <sub>2</sub> O <sub>3</sub>	BT resin based laminate
Max Body Height (Dim A2 in Datasheet)	1.65mm	1.50mm
Max Overall Height (Dim A in Datasheet)	1.83mm	1.68mm

None

There is no product marking change as a result of this change

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#### **Reliability Data Summary:**

QV DEVICE NAME: <u>\$B3229-E1\$</u>
RMS : <u>P64169</u>
PACKAGE : <u>\$IP-25</u>

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 2V GC5005 TQFP qual vehicle	504 hrs	0/78
HTSL	JESD22-A103	Ta= 150°C	504 hrs	0/231
TC	JESD22-A104	Ta= -40°C to +85°C	100 cyc	0/75 <sup>1</sup>
THB	JESD22-A110	85°C, 85% RH, 1.3V	1008 hrs	0/75
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/75
PC	J-STD-020 JESD-A113	MSL 4 @ 240 °C		
SD	JSTD002	Ta = 245C, 5 sec, E7160 qual vehicle		0/ 15

<sup>1.</sup> Device specific qualification points based on original device qualification.

#### **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

#### **List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Part Number	Qualification Vehicle
SB3229-E1	SB3229-E1
SB3229-E1-T	SB3229-E1
SB3230-E1-T	NA
SB3231-E1	NA
SB3231-E1-T	NA

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